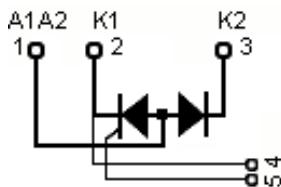


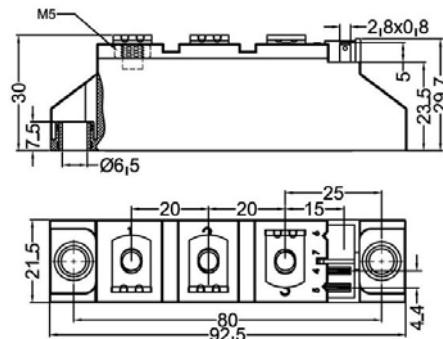
STDA116GKXX

Thyristor-Diode Common Anode Modules



| Type | VRSM VDSM V | VRRM VDRM V |
|-------------|-------------------|-------------------|
| STDA116GK08 | 900 | 800 |
| STDA116GK12 | 1300 | 1200 |
| STDA116GK14 | 1500 | 1400 |
| STDA116GK16 | 1700 | 1600 |
| STDA116GK18 | 1900 | 1800 |

Dimensions in mm (1mm=0.0394")



| Symbol | Test Conditions | Maximum Ratings | Unit |
|--|---|---------------------------------|------------|
| I_{TRMS} , I_{FRMS} I_{TAVM} , I_{FAVM} | $T_{VJ}=T_{VJM}$ $T_c=85^\circ C$; 180° sine | 180 116 | A |
| I_{TSM} , I_{FSM} | $T_{VJ}=45^\circ C$ $V_R=0$ | 2250 2400 | A |
| | $T_{VJ}=T_{VJM}$ $V_R=0$ | 2000 2150 | |
| $\int i^2 dt$ | $T_{VJ}=45^\circ C$ $V_R=0$ | 25300 23900 | $A^2 s$ |
| | $T_{VJ}=T_{VJM}$ $V_R=0$ | 20000 19100 | |
| $(di/dt)_{cr}$ | $T_{VJ}=T_{VJM}$ $f=50Hz$, $t_p=200\mu s$ $V_D=2/3V_{DRM}$ $I_G=0.45A$ $dI/dt=0.45A/\mu s$ | 150 | $A/\mu s$ |
| | repetitive, $I_T=250A$ non repetitive, $I_T=I_{TAVM}$ | 500 | |
| $(dv/dt)_{cr}$ | $T_{VJ}=T_{VJM}$; $V_{DR}=2/3V_{DRM}$ $R_{GK}=\infty$; method 1 (linear voltage rise) | 1000 | V/ μs |
| P_{GM} | $T_{VJ}=T_{VJM}$ $I_T=I_{TAVM}$ | 10 5 | W |
| P_{GAV} | | 0.5 | W |
| V_{RGM} | | 10 | V |
| T_{VJ} T_{VJM} T_{stg} | | -40...+125 125 -40...+125 | °C |
| V_{ISOL} | 50/60Hz, RMS $I_{ISOL}\leq 1mA$ | 3000 3600 | V~ |
| M_d | Mounting torque (M5) Terminal connection torque (M5) | 2.5-4.0/22-35 2.5-4.0/22-35 | Nm/lb.in. |
| Weight | Typical | 78 | g |

Sirectifier®

STDA116GKXX

Thyristor-Diode Common Anode Modules

| Symbol | Test Conditions | Characteristic Values | Unit |
|--------------------|---|-----------------------|-----------|
| I_{RRM}, I_{DRM} | $V_{VJ}=V_{VJM}; V_R=V_{RRM}; V_D=V_{DRM}$ | 5 | mA |
| V_T, V_F | $I_T, I_F=300A; V_{VJ}=25^\circ C$ | 1.5 | V |
| V_{TO} | For power-loss calculations only ($T_{VJ}=125^\circ C$) | 0.8 | V |
| r_T | | 2.4 | $m\Omega$ |
| V_{GT} | $V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$ | 2.5 2.6 | V |
| I_{GT} | $V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$ | 150 200 | mA |
| V_{GD} | $T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$ | 0.2 | V |
| I_{GD} | | 10 | mA |
| I_L | $T_{VJ}=25^\circ C; t_p=10\mu s; V_D=6V$ $I_G=0.45A; dI/dt=0.45A/\mu s$ | 450 | mA |
| I_H | $T_{VJ}=25^\circ C; V_D=6V; R_{GK}=\infty$ | 200 | mA |
| t_{gd} | $T_{VJ}=25^\circ C; V_D=1/2V_{DRM}$ $I_G=0.45A; dI/dt=0.45A/\mu s$ | 2 | us |
| t_q | $T_{VJ}=T_{VJM}; I_T=150A; t_p=200\mu s; -dI/dt=10A/\mu s$ $V_R=100V; dv/dt=20V/\mu s; V_D=2/3V_{DRM}$ | typ. 185 | us |
| Q_s | $T_{VJ}=T_{VJM}; I_T, I_F=50A; -dI/dt=6A/\mu s$ | 170 | uC |
| I_{RM} | | 45 | A |
| R_{thJC} | per thyristor/diode; DC current per module | 0.22 0.11 | K/W |
| R_{thJK} | per thyristor/diode; DC current per module | 0.42 0.21 | K/W |
| ds | Creeping distance on surface | 12.7 | mm |
| da | Strike distance through air | 9.6 | mm |
| a | Maximum allowable acceleration | 50 | m/s^2 |

FEATURES

- * International standard package
- * DCB base plate
- * Glass passivated chips
- * Isolation voltage 3600 V~
- * UL File NO.E310749
- * RoHS compliant

APPLICATIONS

- * DC motor control
- * Softstart AC motor controller
- * Light, heat and temperature control

ADVANTAGES

- * Space and weight savings
- * Simple mounting with two screws
- * Improved temperature and power cycling
- * Reduced protection circuits

STDA116GKXX

Thyristor-Diode Common Anode Modules

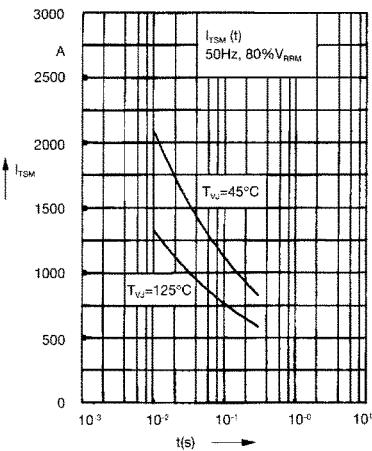


Fig. 1 Surge overload current
 I_{TSM}, I_{FSM} : Crest value, t: duration

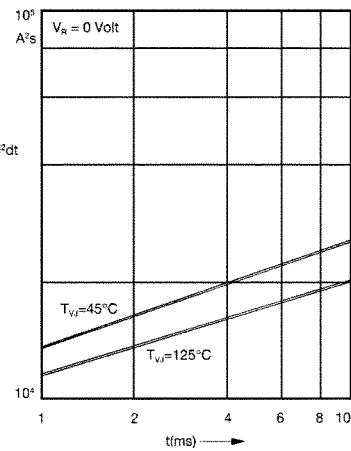


Fig. 2 $\int i^2 dt$ versus time (1-10 ms)

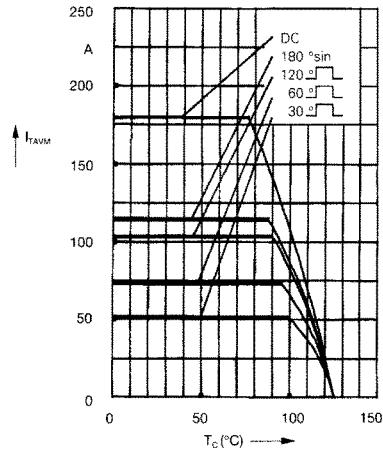


Fig. 2a Maximum forward current at case temperature

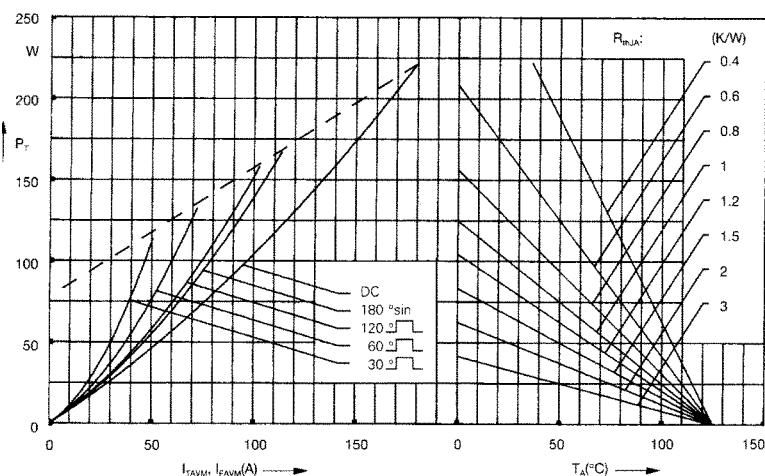


Fig. 3 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

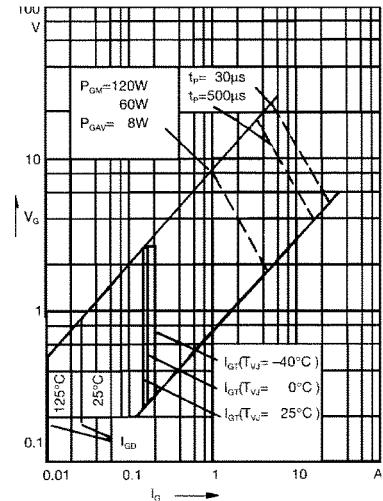


Fig. 4 Gate trigger characteristics

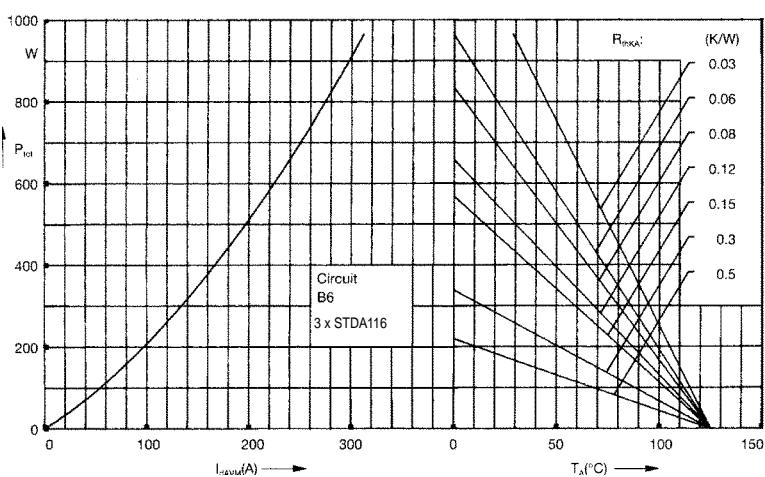


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

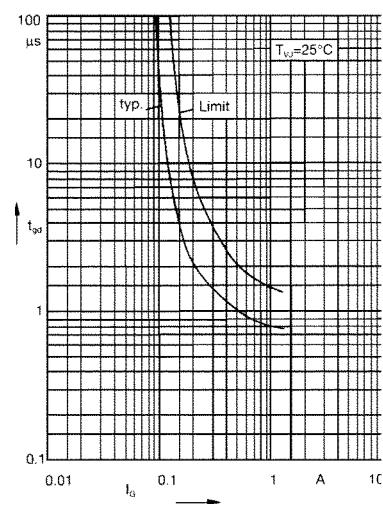


Fig. 6 Gate trigger delay time

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Thyristor-Diode Common Anode Modules

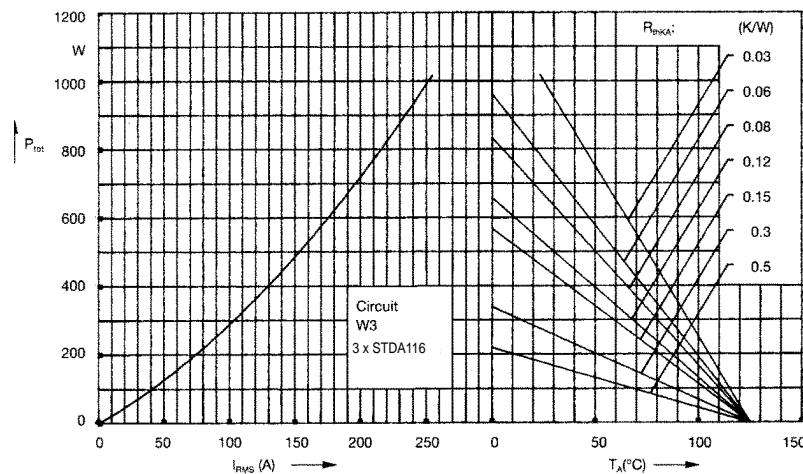


Fig. 7 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

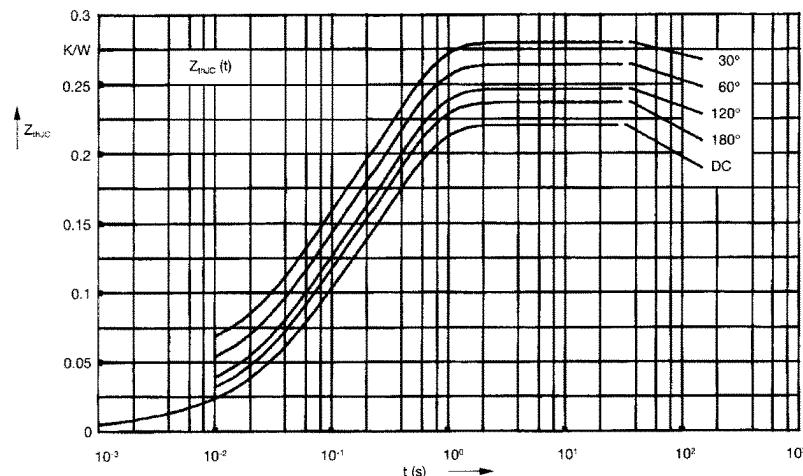


Fig. 8 Transient thermal impedance
junction to case (per thyristor or
diode)

R_{thJC} for various conduction angles d:

| d | R_{thJC} (K/W) |
|-------|------------------|
| DC | 0.22 |
| 180°C | 0.23 |
| 120°C | 0.25 |
| 60°C | 0.27 |
| 30°C | 0.28 |

Constants for Z_{thJC} calculation:

| i | R_{thi} (K/W) | t_i (s) |
|---|-----------------|-----------|
| 1 | 0.0066 | 0.0019 |
| 2 | 0.0678 | 0.0477 |
| 3 | 0.1456 | 0.344 |

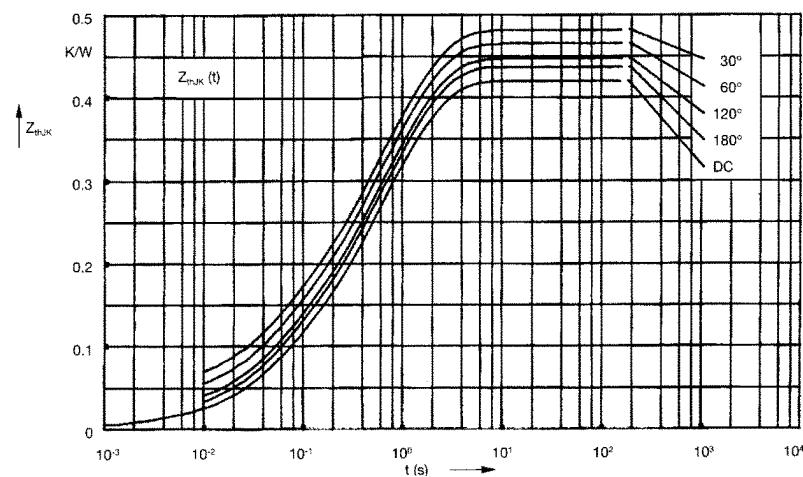


Fig. 9 Transient thermal impedance
junction to heatsink (per thyristor
or diode)

R_{thJK} for various conduction angles d:

| d | R_{thJK} (K/W) |
|-------|------------------|
| DC | 0.42 |
| 180°C | 0.43 |
| 120°C | 0.45 |
| 60°C | 0.47 |
| 30°C | 0.48 |

Constants for Z_{thJK} calculation:

| i | R_{thi} (K/W) | t_i (s) |
|---|-----------------|-----------|
| 1 | 0.0066 | 0.0019 |
| 2 | 0.0678 | 0.0477 |
| 3 | 0.1456 | 0.344 |
| 4 | 0.2 | 1.32 |